

Features

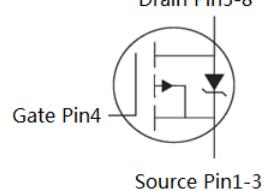
- P-Channel, -5V Logic Level Control
- Enhancement mode
- Very low on-resistance $R_{DS(on)}$ @ $V_{GS}=-4.5$ V
- Fast Switching
- 100% Avalanche Tested
- Pb-free lead plating; RoHS compliant; Hg-Free

V_{DS}	-100	V
$R_{DS(on),TYP}@ V_{GS}=-10$ V	36	mΩ
$R_{DS(on),TYP}@ V_{GS}=-4.5$ V	38	mΩ
I_D	-30	A

PDFN5x6



Part ID	Package Type	Marking	Tape and reel information
VSP040P10MS	PDFN5x6	040P10M	3000pcs/reel



Absolute Maximum Ratings

Symbol	Parameter	Rating	Unit
Common Ratings (T_c=25°C Unless Otherwise Noted)			
V_{GS}	Gate-Source Voltage	±20	V
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	-100	V
T_{STG} T_J	Storage and operating temperature range①	-55 to 150	°C
I_S	Diode Continuous Forward Current	$T_c=25^\circ\text{C}$	-30
Mounted on Large Heat Sink			
I_{DM}	Pulse Drain Current Tested ①	$T_c=25^\circ\text{C}$	-120
I_D	Continuous Drain current@ $V_{GS}=10$ V	$T_c=25^\circ\text{C}$	-30
P_D	Maximum Power Dissipation	$T_c=25^\circ\text{C}$	73
$R_{\theta JC}$	Thermal Resistance-Junction to Case	1.7	°C/W
$R_{\theta JA}$	Thermal Resistance Junction-Ambient($t_s < 10$ s)	50	°C/W
Drain-Source Avalanche Ratings			
EAS	Avalanche Energy, Single Pulsed ②	306	mJ

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
Static Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise stated)						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=-250\mu\text{A}$	-100	--	--	V
I_{DSS}	Zero Gate Voltage Drain Current($T_c=25^\circ\text{C}$)	$V_{\text{DS}}=-100\text{V}, V_{\text{GS}}=0\text{V}$	--	--	-1	μA
	Zero Gate Voltage Drain Current($T_c=125^\circ\text{C}$)	$V_{\text{DS}}=-100\text{V}, V_{\text{GS}}=0\text{V}$	--	--	-10	μA
I_{GSS}	Gate-Body Leakage Current	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{V}$	--	--	± 100	nA
$V_{\text{GS}(\text{TH})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=-250\mu\text{A}$	-1.0	-2.0	-3.0	V
$R_{\text{DS}(\text{ON})}$	Drain-Source On-State Resistance ^③	$V_{\text{GS}}=-10\text{V}, I_{\text{D}}=-30\text{A}$	--	36	45	$\text{m}\Omega$
$R_{\text{DS}(\text{ON})}$	Drain-Source On-State Resistance ^③	$V_{\text{GS}}=-4.5\text{V}, I_{\text{D}}=-15\text{A}$	--	38	50	$\text{m}\Omega$
Dynamic Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise stated)						
C_{iss}	Input Capacitance	$V_{\text{DS}}=-30\text{V}, V_{\text{GS}}=0\text{V}, f=1\text{MHz}$	--	6590	--	pF
C_{oss}	Output Capacitance		--	225	--	pF
C_{rss}	Reverse Transfer Capacitance		--	175	--	pF
Q_g	Total Gate Charge	$V_{\text{DS}}=-50\text{V}, I_{\text{D}}=-10\text{A}, V_{\text{GS}}=-10\text{V}$	--	69	--	nC
Q_{gs}	Gate-Source Charge		--	14	--	nC
Q_{gd}	Gate-Drain Charge		--	19	--	nC
Switching Characteristics						
$t_{\text{d(on)}}$	Turn-on Delay Time	$V_{\text{DD}}=-50\text{V}, I_{\text{D}}=-1\text{A}, R_{\text{G}}=6.8\Omega, V_{\text{GS}}=-10\text{V}$	--	22	--	nS
t_r	Turn-on Rise Time		--	26	--	nS
$t_{\text{d(off)}}$	Turn-Off Delay Time		--	74	--	nS
t_f	Turn-Off Fall Time		--	66	--	nS
Source- Drain Diode Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise stated)						
I_{SD}	Source-drain current(Body Diode)	$T_c=25^\circ\text{C}$	--	--	-30	A
V_{SD}	Forward on voltage	$I_{\text{SD}}=-30\text{A}, V_{\text{GS}}=0\text{V}$	--	0.90	-1.3	V
t_{rr}	Reverse Recovery Time	$T_j=25^\circ\text{C}, I_{\text{sd}}=-10\text{A}, V_{\text{GS}}=0\text{V}$ $dI/dt=-500\text{A}/\mu\text{s}$	--	52	--	nS
Q_{rr}	Reverse Recovery Charge			128		nC

NOTE:

① Repetitive rating; pulse width limited by max. junction temperature.

② Limited by $T_{J\text{max}}$, starting $T_J = 25^\circ\text{C}$, $L = 0.5\text{mH}$, $R_G = 25\Omega$, $I_{AS} = -35\text{A}$, $V_{GS} = -10\text{V}$. Part not recommended for use above this value

③ Pulse width $\leq 300\mu\text{s}$; duty cycle $\leq 2\%$.

Typical Characteristics

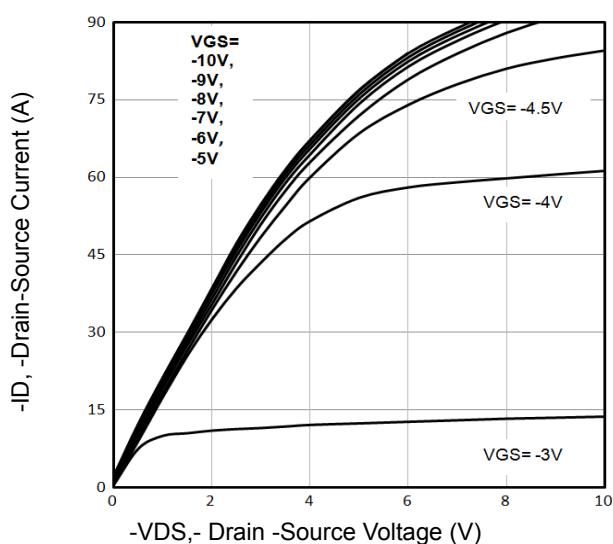


Fig1. Typical Output Characteristics

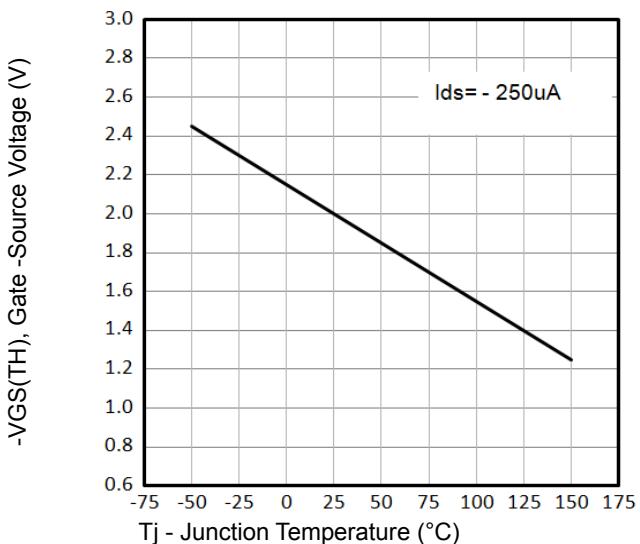


Fig2. $-V_{GS(TH)}$ Gate -Source Voltage Vs. Tj

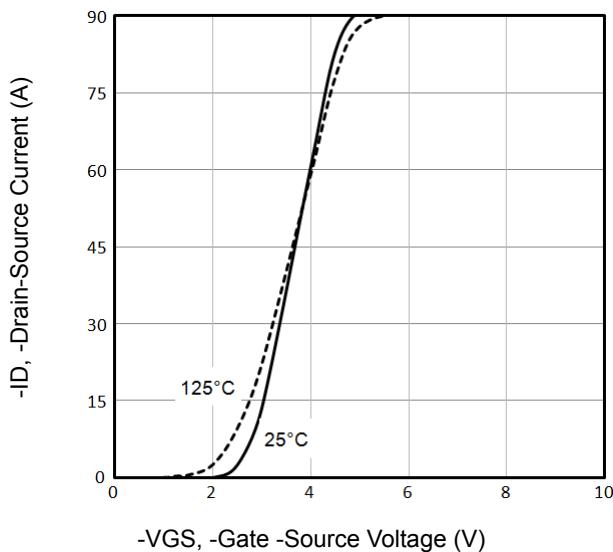


Fig3. Typical Transfer Characteristics

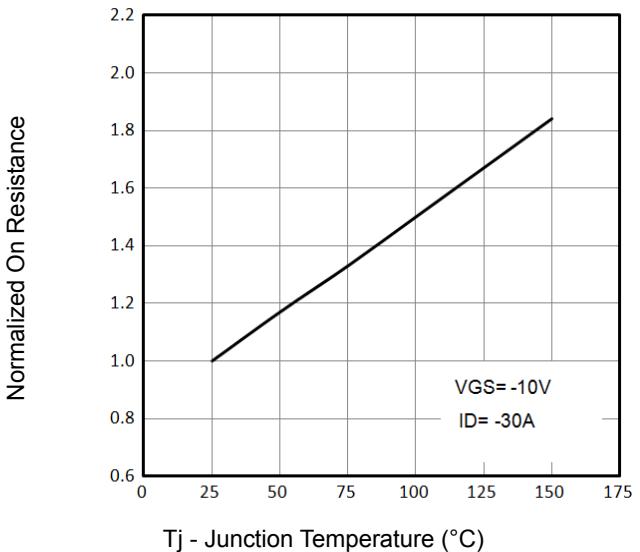


Fig4. Normalized On-Resistance Vs. Tj

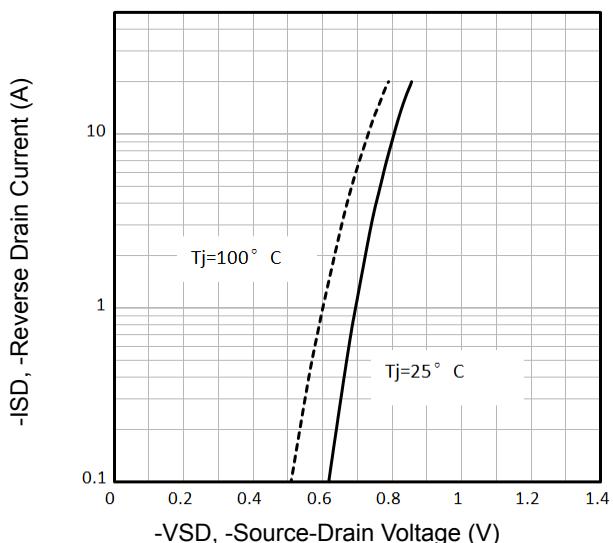


Fig5. Typical Source-Drain Diode Forward Voltage

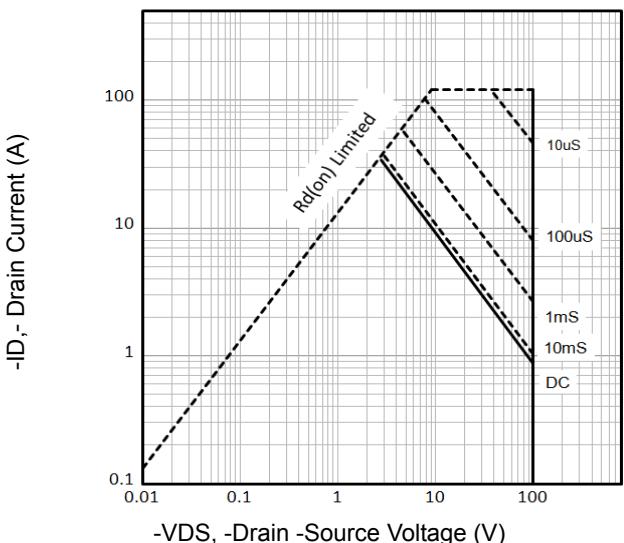


Fig6. Maximum Safe Operating Area

Typical Characteristics

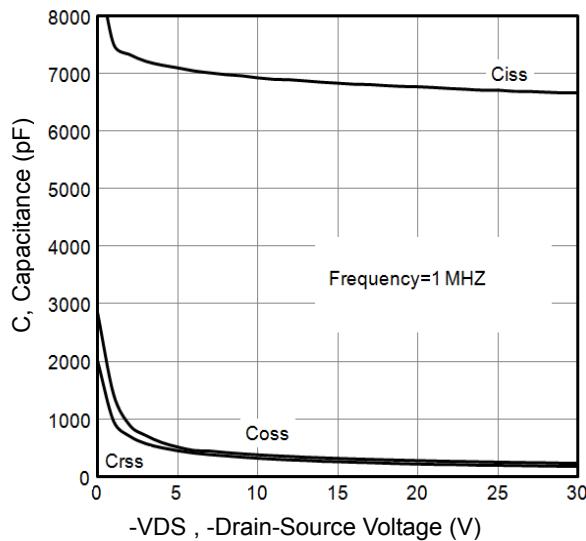


Fig7. Typical Capacitance Vs.Drain-Source Voltage

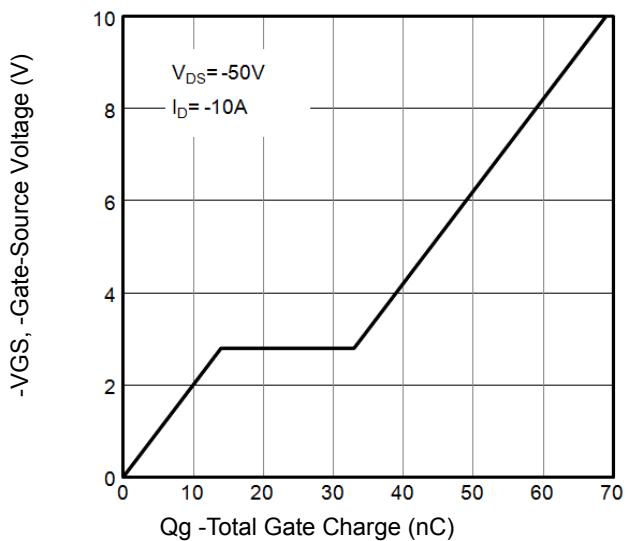


Fig8. Typical Gate Charge Vs.Gate-Source Voltage

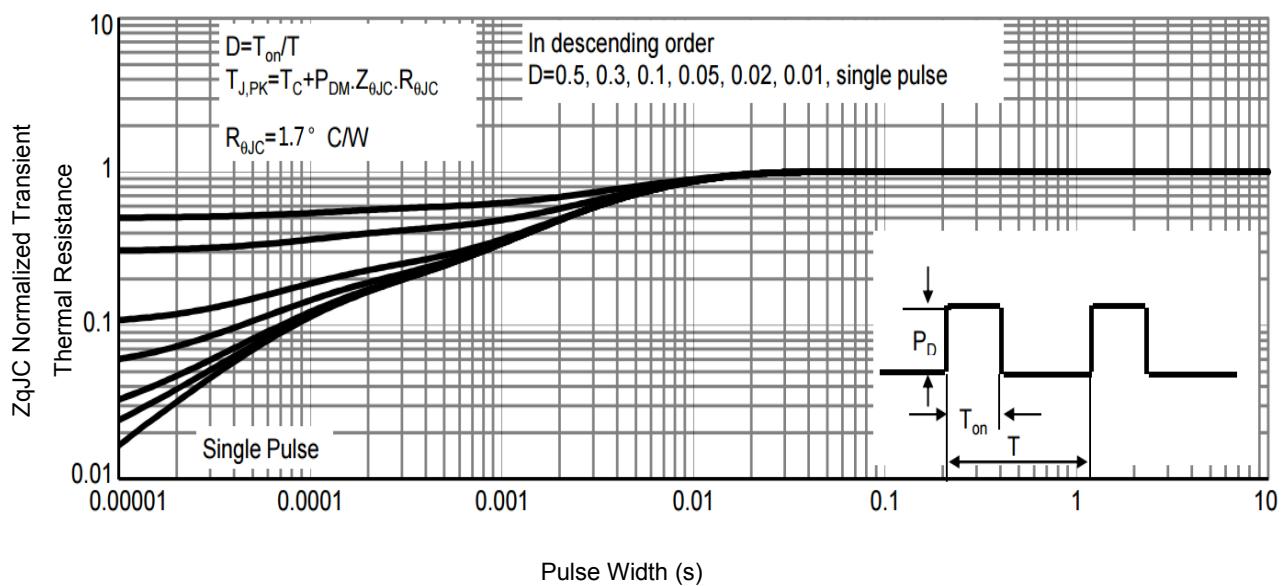


Fig9. Normalized Maximum Transient Thermal Impedance

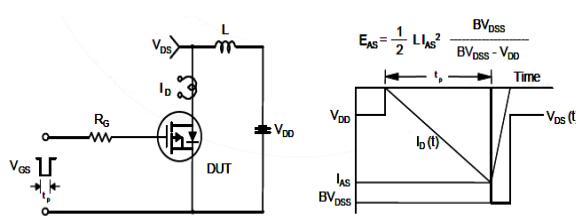


Fig10. Unclamped Inductive Test Circuit and Waveforms

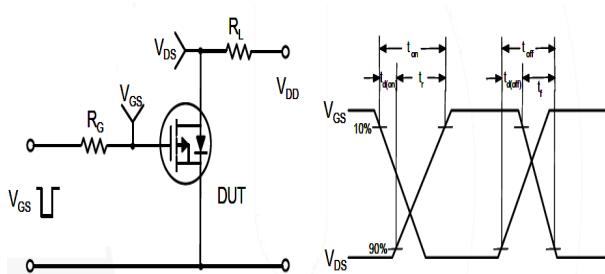
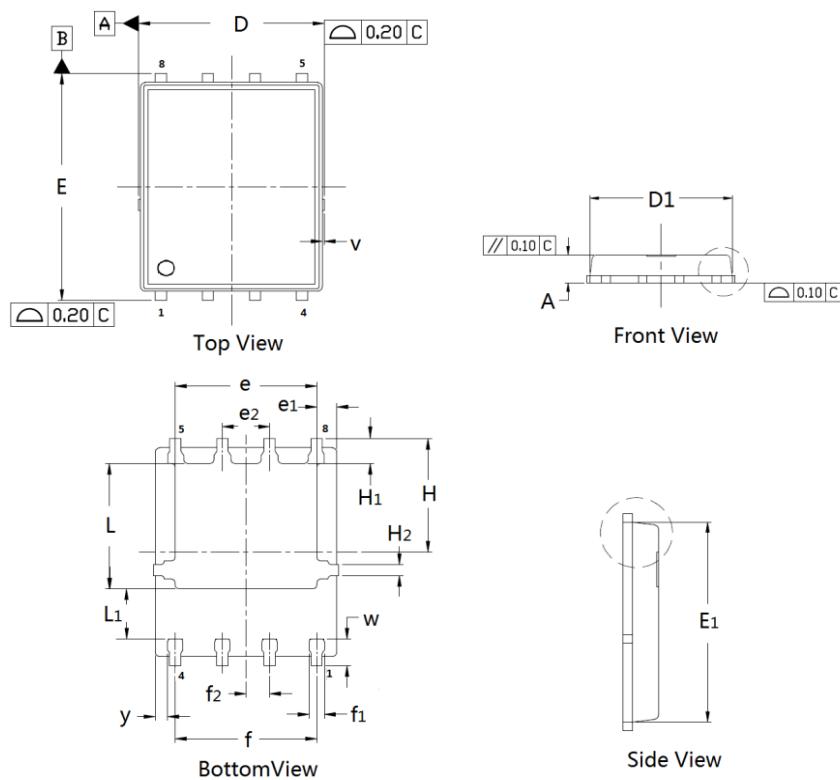


Fig11. Switching Time Test Circuit and waveforms

PDFN5×6 Package Outline Data



DIMENSIONS (unit : mm)

Symbol	Min	Typ	Max	Symbol	Min	Typ	Max
A	0.90	1.02	1.10	D	4.90	4.98	5.10
D ₁	4.80	4.89	5.00	E	6.00	6.11	6.20
E ₁	5.65	5.74	5.85	e	3.72	3.80	3.92
e ₁	--	0.54	--	e ₂	--	1.27	--
f	--	3.82	--	f ₁	0.31	0.37	0.51
f ₂	--	0.64	--	H	--	3.15	--
H ₁	0.59	0.63	0.79	H ₂	0.26	0.28	0.32
L	3.38	3.45	3.58	L ₁	--	1.39	--
v	--	0.13	--	w	0.64	0.68	0.84
y	--	0.34	--		--	--	--

Customer Service

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